

rev 1.4

Peak EMI Reducing Solution

Features

- Generates an EMI optimized clocking signal at output.
- Input frequency – 14.31818MHz.
- Frequency outputs:
 - 120MHz (modulated) - default.
 - 72MHz (modulated) or 48MHz (modulated) selectable via I2C
- $\pm 1\%$ Centre spread.
- Modulation rate: 40KHz.
- Byte Write via I2C
- Supply voltage range $3.3V \pm 0.3V$.
- Available in 8-pin SOIC Package.
- Available in Commercial and Industrial Temperature ranges.

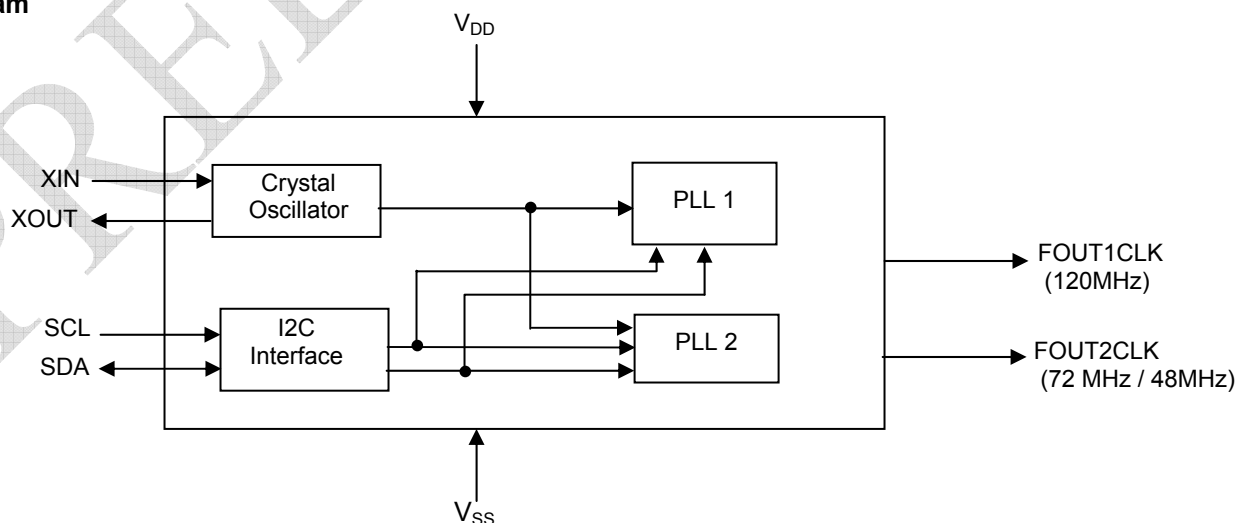
The ASM3P2508A allows significant system cost savings by reducing the number of circuit board layers and shielding that are required to pass EMI regulations. The ASM3P2508A modulates the output of PLL in order to spread the bandwidth of a synthesized clock, thereby decreasing the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most clock generators. Lowering EMI by increasing a signal's bandwidth is called spread spectrum clock generation.

The ASM3P2508A has a feature to power down the 72MHz/48MHz output by writing data into specific registers in the device via I2C. By writing a '0' into bit 1 of Byte 0, the PLL block generating 72MHz / 48MHz can be powered down. Writing '0' into bit '7' of Byte 1 selects an output of 72 MHz on FOUT2CLK while a '1' at the same location selects a 48 MHz clock output. However, the I2C block, crystal oscillator, and the PLL block generating 120MHz would be always running.

Product Description

The ASM3P2508A is a versatile spread spectrum frequency modulator. The ASM3P2508A reduces electromagnetic interference (EMI) at the clock source.

Block Diagram

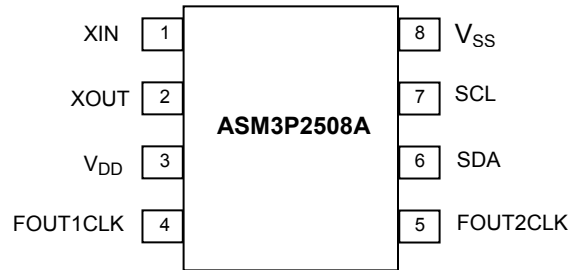


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Pin Configuration



Pin Description

Pin Name	Type	Description
XIN	I	Connection to crystal
XOUT	O	Connection to crystal
V _{DD}	P	Power supply for the analog and digital blocks
FOUT1CLK	O	Clock output-1 (120MHz) - default
FOUT2CLK	O	Clock output-2 (72MHz / 48MHz)
SDA	I/O	I2C Data
SCL	I	I2C Clock
V _{SS}	P	Ground to entire chip

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V _{DD} , V _{IN}	Voltage on any pin with respect to Ground	-0.5 to +4.6	V
T _{STG}	Storage temperature	-40 to +85	°C
T _A	Operating temperature	0 to 70	°C
T _s	Max. Soldering Temperature (10 sec)	260	°C
T _J	Junction Temperature	150	°C
T _{DV}	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	KV

Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

Operating Conditions

Symbol	Parameter	Condition / Description	Min	Typ	Max	Unit
V _{DD}	Supply Voltage	3.3V ± 10%	3	3.3	3.6	V
T _A	Ambient Operating Temperature Range		-10		+70	°C
F _{XIN}	Crystal Resonator Frequency			14.31818		MHz
	Serial Data Transfer Rate	Standard Mode	10		100	Kb/s
C _L	Output Driver Load Capacitance				15	pF

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DC Electrical Characteristics

(Test Condition : All the parameters are measured at room temperature (25°C) , unless otherwise stated)

Parameter	Symbol	Conditions / Description	Min	Typ	Max	Unit
Overall						
Supply Current, Dynamic	I_{CC}	$V_{DD}=3.3V, F_{CLK}=14.31818MHz, C_L=15pF$	40	49	60	mA
Supply Current, Static	I_{DD}	$V_{DD}=3.3V, \text{Software Power Down}^*$	27	35	43	mA
All input pins						
High-Level Input Voltage	V_{IH}	$V_{DD}=3.3V$	2.0	-	$V_{DD}+0.3$	V
Low-Level Input Voltage	V_{IL}	$V_{DD}=3.3V$	$V_{SS}-0.3$	-	0.8	V
High-Level Input Current	I_{IH}		-1	-	1	μA
Low-Level Input Current (pull-up)	I_{IL}		-20	-36	-80	μA
Clock Outputs (FOUT1CLK, FOUT2CLK)						
High-Level Output Voltage	V_{OH}	$V_{DD}=3.3V, I_{OH}=20mA$	2.5	-	3.3	V
Low-Level Output Voltage	V_{OL}	$V_{DD}=3.3V, I_{OL}=20mA$	0	-	0.4	V
Output Impedance	Z_{OH}	$V_O=0.5V_{DD}; \text{output driving high}$	-	29	-	Ω
	Z_{OL}	$V_O=0.5V_{DD}; \text{output driving low}$	-	27	-	

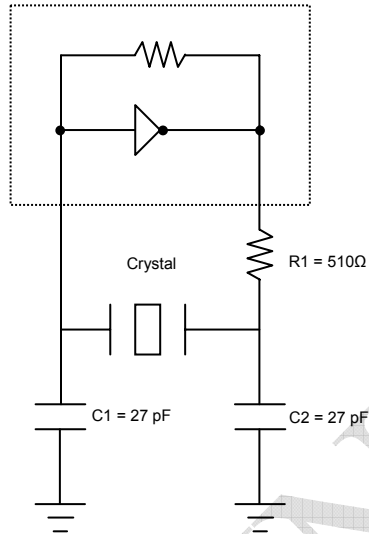
* FOUT1CLK (120MHz) is functional and not loaded

AC Electrical Characteristics

Parameter	Symbol	Conditions/ Description	Min	Typ	Max	Unit	
Rise Time	t_r	$V_O = 0.8V \text{ to } 2.0V; C_L = 15pF$	FOUT1CLK	640	680	750	pS
			FOUT2CLK	440	480	600	
Fall Time	t_f	$V_O = 2.0V \text{ to } 0.8V; C_L = 15pF$	FOUT1CLK	660	720	800	pS
			FOUT2CLK	460	520	570	
Clock Duty Cycle	t_D	Ratio of pulse width (as measured from rising edge to next falling edge at 2.5V) to one clock period	45	-	55	%	
Frequency Deviation	f_D	Output Frequency =120MHz	-	± 2.73	-	%	
		Output Frequency =72MHz /48 MHz	-	± 1.78	-		
Jitter, Long Term	$T_j (LT)$	On rising edges 500 μs apart at 2.5 V relative to an ideal clock, PLL B inactive *	-	45	-	pS	
		On rising edges 500 μs apart at 2.5 V relative to an ideal clock, PLL B active *	-	165	-		
Jitter, peak to peak	$T_j (\Delta T)$	From rising edge to next rising edge at 2.5 V, PLL B inactive *	-	110	-	pS	
		From rising edge to next rising edge at 2.5 V, PLL B active *	-	390	-		
Clock Stabilization Time	t_{STB}	Output active from power up, RUN Mode via Software Power Down	-	125	-	μs	

 * $C_L = 15 pF, F_{in} = 14.31818MHz$

Typical Crystal Oscillator Circuit



Typical Crystal Specifications

Fundamental AT cut parallel resonant crystal	
Nominal Frequency	14.31818MHz
Frequency Tolerance	+/- 50 ppm or better at 25°C
Operating temperature range	-20°C to +85°C
Storage Temperature	-40°C to +85°C
Load Capacitance	18pF
Shunt capacitance	7 pF maximum
ESR	25 Ω

I2C Serial Interface Information

The information in this section assumes familiarity with I2C programming.

How to program ASM3P2508A through I2C:

- Master (host) sends a start bit.
- Master (host) sends the write address D4 (H).
- ASM3P2508A device will acknowledge.
- Master (host) sends the beginning byte location (N = 0, 1).
- ASM3P2508A device will acknowledge.
- Master (host) sends a byte count (X = 1,2)
- ASM3P2508A device will acknowledge.
- Master (host) starts sending byte N through byte (N+X – 1)
- ASM3P2508A device will acknowledge each byte one at a time.
- Master (host) sends a Stop bit.

How to Read from ASM3P2508A through I2C:

- Master (host) will send start bit.
- Master (host) sends the write address D4 (H).
- ASM3P2508A device will acknowledge.
- Master (host) sends the beginning byte location (N = 0, 1).
- ASM3P2508A device will acknowledge.
- Master (host) will send a separate start bit.
- Master (host) sends the read address D5 (H).
- ASM3P2508A device will acknowledge.
- ASM3P2508A device will send the byte count (X = 1, 2).
- Master (host) acknowledges.
- ASM3P2508A device sends byte N through byte (N+X – 1).
- Master (host) will need to acknowledge each byte.
- Master (host) will send a stop bit.

Controller (Host)	ASM3P2508A (slave/receiver)
Start Bit	
Slave Address D4(H)	
	ACK
Beginning byte location (=N)	
	ACK
Byte count (=X)	
	ACK
Beginning byte (Byte N)	
	ACK
Next Byte (Byte N+1)	
	ACK
-----	----
Last Byte (Byte N+X-1)	
	ACK
Stop Bit	

Controller (Host)	ASM3P2508A (slave/receiver)
Start Bit	
Slave Address D4(H)	
	ACK
Beginning Byte = N	
	ACK
Repeat start	
Slave address D5(H)	
	ACK
	Byte Count (= X)
ACK	
	Beginning byte N
ACK	
	Next Byte N+1
ACK	

	Last Byte (Byte N+X-1)
Not Acknowledge	
Stop Bit	

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An example of a Byte Write via I2C to partially 'power down' the device:

ASM3P2508A can be partially 'powered down' using bit 1 of Byte 0. The organization of the register bits for Byte '0' is given with default values below:

Bit							
7	6	5	4	3	2	1	0
Resv	Resv	Resv	Resv	Resv	Resv	PLL2 Enable	PLL1 Enable
0	1	0	1	0	1	1	1

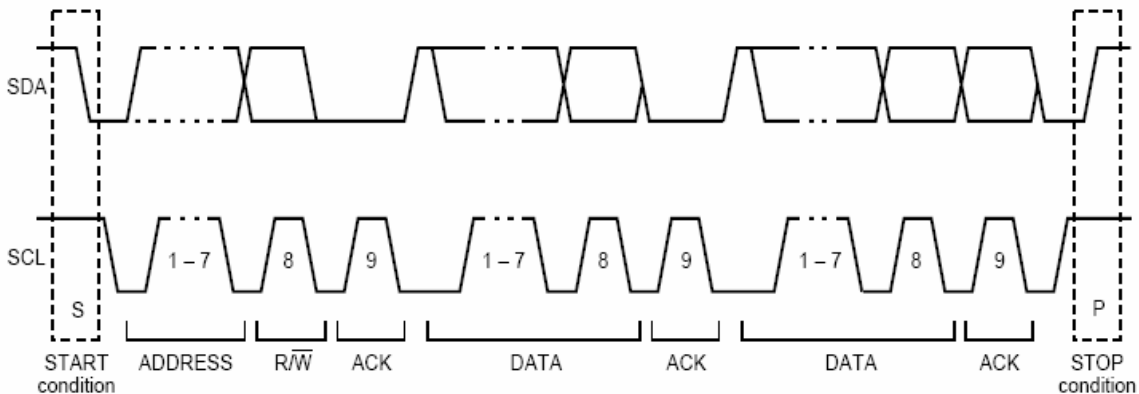
57 (H). To put ASM3P2508A in 'power down' mode, the bit 1 of Byte 0 is to be changed to logic '0'. Hence writing a 55 (H) via I2C into Byte 0 would put the device in partial 'power down' mode where the PLL block generating 72 MHz / 48 MHz would be powered down while I2C block, crystal oscillator, and the PLL block generating 120 MHz would still be active. The organization of the register bits is as below:

Bit							
7	6	5	4	3	2	1	0
Resv	Resv	Resv	Resv	Resv	Resv	PLL2 Enable	PLL1 Enable
0	1	0	1	0	1	0	1

The function of partial power down of the device is of interest to us - that is bit 1 of Byte 0. In the default mode this bit is logic '1'. As such, the Byte 0 default value is

	Byte 0	Byte 1	FOUT1CLK (MHz)	FOUT2CLK(MHz)
Power up default	6F(H)	3F(H)	120	72
48_MHz Mode	6F(H)	BF(H)	120	48
Power down PLL with 72MHz	6D(H)	3F(H)	120	-
Power down PLL with 48MHz	6D(H)	BF(H)	120	-

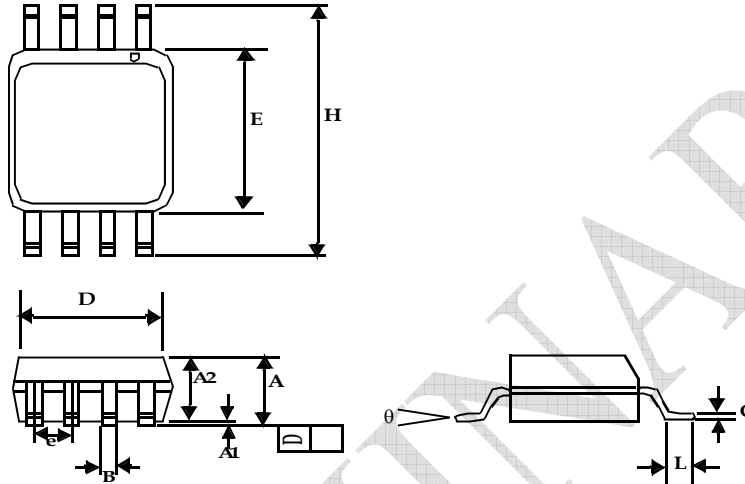
Figure showing a complete data transfer:



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Package Information

8-lead (150-mil) SOIC Package



Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A1	0.004	0.010	0.10	0.25
A	0.053	0.069	1.35	1.75
A2	0.049	0.059	1.25	1.50
B	0.012	0.020	0.31	0.51
C	0.007	0.010	0.18	0.25
D	0.193 BSC		4.90 BSC	
E	0.154 BSC		3.91 BSC	
e	0.050 BSC		1.27 BSC	
H	0.236 BSC		6.00 BSC	
L	0.016	0.050	0.41	1.27
θ	0°	8°	0°	8°

Ordering Codes

Part number	Marking	Package Configuration	Temperature
ASM3P2508AG-08ST	3P2508AG	8-PIN SOIC, TUBE, Green	Commercial
ASM3P2508AG-08SR	3P2508AG	8-PIN SOIC, TAPE AND REEL, Green	Commercial
ASM3I2508AG-08ST	3I2508AG	8-PIN SOIC, TUBE, Green	Industrial
ASM3I2508AG-08SR	3I2508AG	8-PIN SOIC, TAPE AND REEL, Green	Industrial
ASM3P2508AF-08ST	3P2508AF	8-PIN SOIC, TUBE, Pb Free	Commercial
ASM3P2508AF-08SR	3P2508AF	8-PIN SOIC, TAPE AND REEL, Pb Free	Commercial
ASM3I2508AF-08ST	3I2508AF	8-PIN SOIC, TUBE, Pb Free	Industrial
ASM3I2508AF-08SR	3I2508AF	8-PIN SOIC, TAPE AND REEL, Pb Free	Industrial

Device Ordering Information

A S M 3 P 2 5 0 8 A F - 0 8 S R

R = Tape & Reel, T = Tube or Tray

O = SOT	U = MSOP
S = SOIC	E = TQFP
T = TSSOP	L = LQFP
A = SSOP	U = MSOP
V = TVSOP	P = PDIP
B = BGA	D = QSOP
Q = QFN	X = SC-70

DEVICE PIN COUNT

F = LEAD FREE AND RoHS COMPLIANT PART
G = GREEN PACKAGE, LEAD FREE, and RoHS

PART NUMBER

X= Automotive (-40C to +125C)	I= Industrial (-40C to +85C)	P or n/c = Commercial (0C to +70C)
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1 = Reserved	6 = Power Management
2 = Non PLL based	7 = Power Management
3 = EMI Reduction	8 = Power Management
4 = DDR support products	9 = Hi Performance
5 = STD Zero Delay Buffer	0 = Reserved

PulseCore Semiconductor Mixed Signal Product

Licensed under US patent #5,488,627, #6,646,463 and #5,631,920.



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Preliminary Information
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Document Version: v1.3

Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to PulseCore Semiconductor, dated 11-11-2003

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